

NN514265 / NN514265A series
EDO (Hyper Page) Mode
CMOS 256K × 16bit Dynamic RAM

NPNX

DESCRIPTION

Preliminary Specification

The NN514265/A series is a high performance CMOS Dynamic Random Access Memory organized as 262,144 words by 16 bits. The NN514265/A series is fabricated with advanced CMOS technology and designed with innovative design techniques resulting in high speed, extremely low power and wide operating margins at both component and system levels.

The NN514265/A series features an EDO (Hyper Page) mode operation in which a high speed read, write or read-write is performed on any column address along a row address.

An extremely short row address capture time and an asynchronous column address decoder relax the timing constraints associated with address multiplexing.

Refresh is accomplished by performing RAS only refresh cycles, hidden refresh cycles, CAS before RAS refresh cycles, or normal read or write cycles on the 512 address combinations of A0 to A8 during a 8 ms period.

Multiplexed address inputs permit The NN514265/A series to be packaged in a standard 40-pin plastic SOJ, 44-pin plastic TSOP TYPEII. The package sizes provide high system bit densities and are compatible with widely available automated testing and insertion equipment. System level features include single power supply of 5V ±10% tolerance and direct interface with high performance TTL logic families.

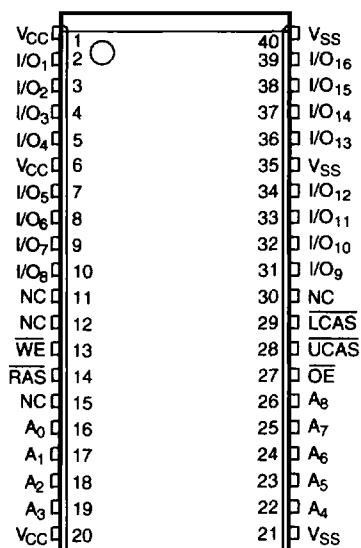
FEATURES

- 262,144 × 16 bit Organization
- Single 5V ±10% Power Supply
- Performance Ranges

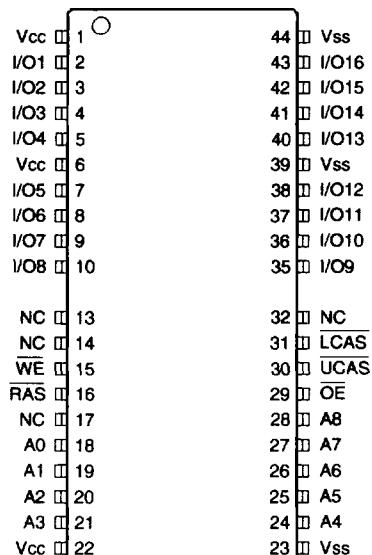
Parameter	-45	-50	-60	-70
Max. RAS Access Time (t_{RAC})	45ns	50ns	60ns	70ns
Max. CAS Access Time (t_{CAC})	15ns	15ns	15ns	20ns
Max. Column Address Access Time (t_{AA})	23ns	25ns	30ns	35ns
Min. Read/Write Cycle Time (t_{RC})	80ns	90ns	110ns	130ns

- EDO (Hyper Page) Mode Operation
- Separate CAS (UCAS, LCAS) for Byte Selection
- Byte Read/Write Mode Operation
- Low Power Operation
 - Low Standby Current (CMOS level inputs)
 - Standard 1mA
 - L version 100μA
- 512 Refresh Cycles
 - Standard distributed across 8ms
 - L version distributed across 128ms
- Self Refresh Mode (L version)
- All inputs/Outputs and Clocks fully TTL and CMOS compatible
- Refresh Modes
 - RAS only
 - CAS before RAS
 - Hidden Refresh
- High Reliability Package
 - Plastic 40pin SOJ (P40SJ-2B0)
 - Plastic 44pin TSOP TYPEII (P44TP-3B4)

PIN CONFIGURATION (TOP VIEW)



40-pin SOJ (400mil)
P40SJ-2B0

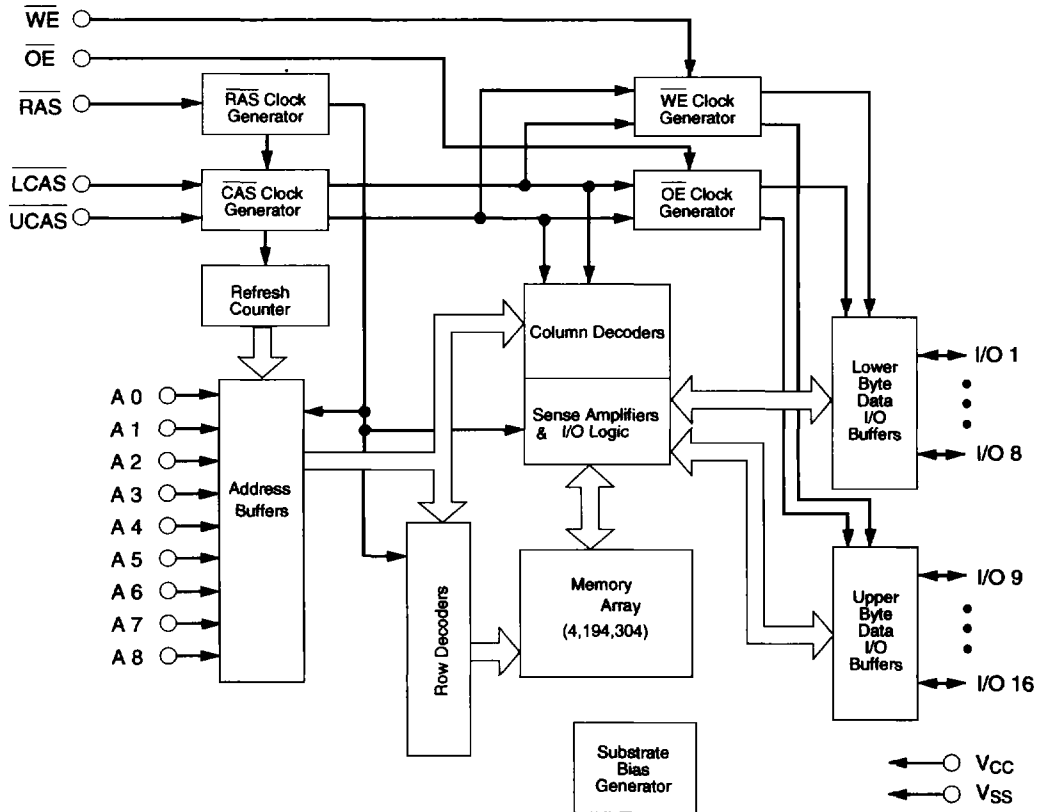


44/40-pin TSOP TYPE (II)
(400mil)
P44TP-3B4

PIN NAMES

A0-A8	Address Inputs
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{UCAS}}$	Column Address Strobe Upper Byte Control
$\overline{\text{LCAS}}$	Column Address Strobe Lower Byte Control
$\overline{\text{OE}}$	Output Enable
I/O1-I/O16	Data-in / Data-out
$\overline{\text{WE}}$	Write Enable
V _{CC}	+5V Supply
V _{SS}	Ground
NC	No Connection

FUNCTIONAL BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

RATING	SYMBOL	VALUE	UNIT
Voltage on Any Pin Relative to V _{SS}	V _{in} , V _{out}	-1 to 7	V
Voltage on V _{CC} Relative to V _{SS}	V _{CC}	-1 to 7	V
Storage Temperature (Plastic)	T _{stg}	-55 to +125	°C
Power Dissipation	P _d	1.0	W
Ambient Operating Temperature	T _a	0 to +70	°C
Short Circuit Output Current	I _{out}	50	mA

Permanent device damage can occur if absolute maximum ratings are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods can affect device reliability.

DC OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
V _{SS}	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage, All Inputs	2.4	—	6.5	V
V _{IL}	Input Low Voltage, All Inputs	-0.5	—	0.8	V

Note: All voltage values in this data sheet are with respect to V_{SS} unless otherwise specified.

DC ELECTRICAL CHARACTERISTICS (0°C ≤ Ta ≤ 70°C, V_{CC} = 5.0V ±10%)

SYMBOL	PARAMETER	SPEED	MIN.	MAX.	UNIT	TEST CONDITIONS	NOTES
I _{CC1}	Operating Current	-45 -50 -60 -70		180 160 150 130	mA mA mA mA	t _{RC} = t _{RC} (min.) RAS, CAS, Address cycling	1, 2
I _{CC2}	Standby Current			1.0	mA	RAS = $\overline{\text{CAS}} \geq (V_{CC} - 0.2V)$	
				2.0	mA	RAS = $\overline{\text{CAS}} \geq V_{IH}$	
I _{CC2}	Standby Current (L version)			100	μA	RAS = $\overline{\text{CAS}} \geq (V_{CC} - 0.2V)$ All other inputs are stable at (V _{CC} - 0.2V) or (V _{SS} + 0.2V)	
I _{CC3}	Refresh Current (RAS only refresh)	-45 -50 -60 -70		180 160 150 130	mA mA mA mA	t _{RC} = t _{RC} (min.) RAS cycling, $\overline{\text{CAS}} = V_{IH}$	1
I _{CC4}	EDO (Hyper Page) Mode Current	-45 -50 -60 -70		125 120 110 100	mA mA mA mA	t _{HPC} = t _{HPC} (min.) RAS = V _{IL} CAS, Address cycling	1,2
I _{CC5}	Refresh Current (CAS before RAS refresh)	-45 -50 -60 -70		180 160 150 130	mA mA mA mA	t _{RC} = t _{RC} (min.) RAS, CAS cycling	1
I _{CC6}	Refresh Current (L version : $\overline{\text{CAS}}$ before RAS refresh)			150	μA	512 cycles / 128ms t _{RAS} ≤ 200ns, WE ≥ (V _{CC} - 0.2V) All other inputs are stable at (V _{CC} - 0.2V) or (V _{SS} + 0.2V)	
I _{CC7}	Self Refresh Mode Current (L version)			150	μA	RAS = $\overline{\text{CAS}} \leq (V_{SS} + 0.2V)$ All other input high levels are (V _{CC} - 0.2V) or input low levels are (V _{SS} + 0.2V)	
I _{IL1}	Input Leakage Current (Any input pin)		-10	10	μA	0V ≤ V _{IH} ≤ 5.5V, Others = 0V	
I _{LO1}	Output Leakage Current (For high impedance state)		-10	10	μA	RAS ≥ V _{IH} (min.), $\overline{\text{CAS}} \geq V_{IH}(\text{min.})$ 0V ≤ V _{OUT} ≤ 5.5V	
V _{OH}	Output High Voltage		2.4		V	I _{OH} = -5.0 mA	
V _{OL}	Output Low Voltage			0.4	V	I _{OL} = 4.2 mA	

Notes: 1. I_{CC1}, I_{CC3}, I_{CC4} and I_{CC5} depend on cycle rate.

2. I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the outputs open.

CAPACITANCE (0°C ≤ Ta ≤ 70°C, V_{CC} = 5.0V ±10%, f = 1MHz)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
C _{IN1}	Address(A0 ~ A8)	—	5	pF
C _{IN2}	RAS, UCAS, LCAS, WE, OE	—	5	pF
C _{OUT}	I/O1 ~ I/O16	—	7	pF

A.C. OPERATING CONDITIONS (0 °C ≤ T_a ≤ 70 °C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V) (NOTES 3, 4, 5)

A.C. TEST CONDITIONS (V_{OH} = 2.0 V, V_{OL} = 0.8 V)

NO.	NOTES		PARAMETER	-45		-50		-60		-70		UNIT	NOTE
	JEDEC	STD.		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	t _{CL1QV}	t _{CAS}	Access Time from CAS	—	15	—	15	—	15	—	20	ns	6,13
2	t _{CH2QV}	t _{CFA}	Access Time from CAS Precharge	—	28	—	30	—	35	—	40	ns	13,14
3	t _{AVQV}	t _{AA}	Access Time from Column Address	—	23	—	25	—	30	—	35	ns	7,13
4	t _{RL1QV}	t _{RAS}	Access Time from RAS	—	45	—	50	—	60	—	70	ns	6,7
5	t _{RL1CH1}	t _{CSH}	CAS Hold Time	30	—	35	—	45	—	55	—	ns	
6	t _{RL1CX}	t _{CHS}	CAS Hold Time (Self Refresh Mode)	-50	—	-50	—	-50	—	-50	—	ns	
7	t _{RL1CH1}	t _{CHR}	CAS Hold Time (CAS before RAS Refresh)	10	—	10	—	10	—	10	—	ns	
8	t _{CH2CL2}	t _{CPN}	CAS Precharge Time (CAS before RAS Refresh)	10	—	10	—	10	—	10	—	ns	
9	t _{CH2CL2}	t _{CP}	CAS Precharge Time (EDO (Hyper Page) Mode)	5	—	5	—	5	—	5	—	ns	14
10	t _{CL1CH1}	t _{CAS}	CAS Pulse Width	8	100K	8	100K	10	100K	15	100K	ns	
11	t _{CL1RL2}	t _{CSR}	CAS Setup Time (CAS before RAS Refresh)	5	—	5	—	5	—	5	—	ns	
12	t _{CL1QX}	t _{CLZ}	CAS to Output in Low-Z	0	—	0	—	0	—	0	—	ns	8
13	t _{CH2RL2}	t _{CRP}	CAS to RAS Precharge Time	5	—	5	—	5	—	5	—	ns	
14	t _{CL1WL2}	t _{CWD}	CAS to WE Delay Time	45	—	45	—	45	—	50	—	ns	11
15	t _{CL1AX}	t _{CAH}	Column Address Hold Time	10	—	10	—	15	—	15	—	ns	
16	t _{RL1AX}	t _{AR}	Column Address Hold Time Referenced to RAS	30	—	35	—	40	—	40	—	ns	
17	t _{AVCL2}	t _{ASC}	Column Address Setup Time	0	—	0	—	0	—	0	—	ns	14
18	t _{AVCH1}	t _{CAL}	Column Address to CAS Lead Time	13	—	13	—	18	—	23	—	ns	
19	t _{AVRH1}	t _{RAL}	Column Address to RAS Lead Time	25	—	27	—	30	—	35	—	ns	
20	t _{AVWL2}	t _{AWD}	Column Address to WE Delay Time	55	—	57	—	60	—	65	—	ns	11
21	t _{CL1DX} t _{WL1DX}	t _{DH}	Data Hold Time	10	—	10	—	10	—	10	—	ns	12
22	t _{CL2QX}	t _{DHC}	Data Output Hold Time (EDO (Hyper Page) Mode)	0	—	0	—	0	—	0	—	ns	
23	t _{QVCL2} t _{QVWL2}	t _{DS}	Data Setup Time	0	—	0	—	0	—	0	—	ns	12
24	t _{CL1QV}	t _{OEA}	OE Access Time	—	15	—	15	—	15	—	20	ns	
25	t _{WL1OL2}	t _{OEH}	OE Command Hold Time	15	—	15	—	15	—	20	—	ns	
26	t _{GH2GL2}	t _{OPZ}	OE Pulse Width for Output Disable When CAS High	5	—	7	—	7	—	7	—	ns	
27	t _{GL1CH1}	t _{OCS}	OE Setup Time to CAS High	5	—	7	—	7	—	7	—	ns	
28	t _{GL1RH1}	t _{ORS}	OE Setup Time to RAS High	5	—	7	—	7	—	7	—	ns	
29	t _{CH2QV}	t _{OED}	OE to Data Delay Time	10	—	10	—	10	—	10	—	ns	
30	t _{GL2QX}	t _{OLZ}	OE to Output in low-Z	0	—	0	—	0	—	0	—	ns	
31	t _{CH2QZ}	t _{OFF}	Output Buffer Turn-off Delay Time	0	12	0	13	0	15	0	15	ns	10
32	t _{OH2QX}	t _{OEZ}	Output Buffer Turn-off Delay Time Referenced to OE	0	10	0	10	0	15	0	15	ns	
33	t _{RHQZ}	t _{OFR}	Output Buffer Turn-off Delay Time Referenced to RAS	0	12	0	13	0	15	0	15	ns	16
34	t _{WL2QZ}	t _{WEZ}	Output Buffer Turn-off Delay Time Referenced to WE	0	12	0	13	0	15	0	15	ns	

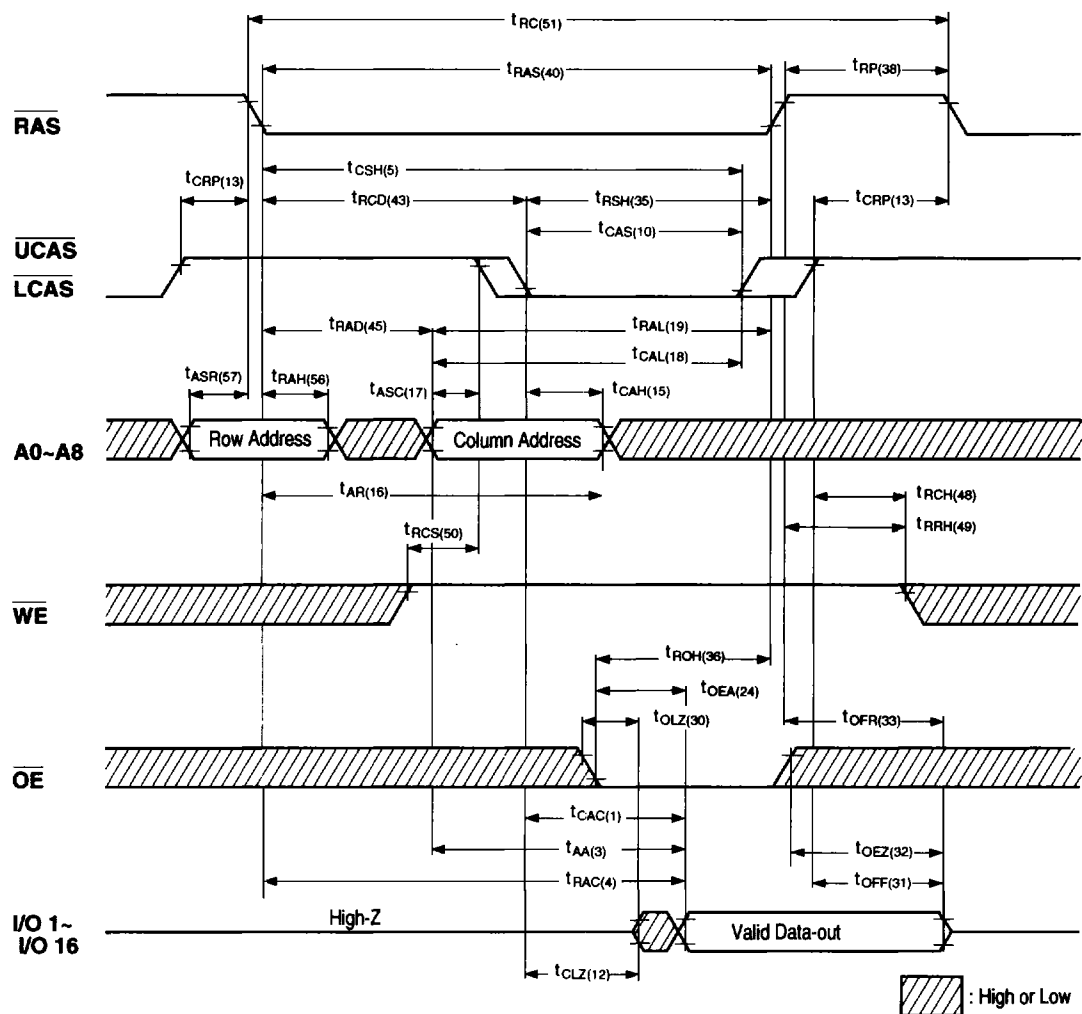
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CMOS 256K × 16bit Dynamic RAM

NO.	SYMBOL		PARAMETER	-45		-50		-60		-70		UNIT	NOTE
	JEDEC	STD.		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
35	t _{CL1RH1}	t _{RS}	RAS Hold Time	15	—	15	—	15	—	20	—	ns	
36	t _{OL1RH1}	t _{ROH}	RAS Hold Time Referenced to OE	10	—	10	—	10	—	10	—	ns	
37	t _{CH2RH1}	t _{RHCP}	RAS Hold Time Referenced CAS Precharge	28	—	30	—	35	—	40	—	ns	
38	t _{RH2RL2}	t _{RP}	RAS Precharge Time	25	—	25	—	30	—	40	—	ns	
39	t _{RH2RL2}	t _{RPS}	RAS Precharge Time (Self Refresh Mode)	80	—	90	—	110	—	130	—		
40	t _{RL1RH1}	t _{RAS}	RAS Pulse Width	45	100K	50	100K	60	100K	70	100K	ns	
41	t _{RL1RH1}	t _{RASS}	RAS Pulse Width (Self Refresh Mode)	300	—	300	—	300	—	300	—	μs	
42	t _{RL1RH1}	t _{RASP}	RAS Pulse Width (EDO (Hyper Page) Mode)	45	100K	50	100K	60	100K	70	100K	ns	
43	t _{RL1CL1}	t _{RCD}	RAS to CAS Delay Time	13	30	13	35	13	45	13	50	ns	6
44	t _{RH2CL2}	t _{RPC}	RAS to CAS Precharge Time	10	—	10	—	10	—	10	—	ns	
45	t _{RL1AV}	t _{RAD}	RAS to Column Address Delay Time	11	20	11	23	11	30	11	35	ns	7
46	t _{RL2OX}	t _{RLZ}	RAS To Output in Low-Z	0	—	0	—	0	—	0	—	ns	
47	t _{RL1WL2}	t _{RWD}	RAS to WE Delay Time	75	—	80	—	90	—	100	—	ns	11
48	t _{CH2WL2}	t _{RCH}	Read Command Hold Time	0	—	0	—	0	—	0	—	ns	9
49	t _{RH2WL2}	t _{RRH}	Read Command Hold Time Referenced to RAS	10	—	10	—	10	—	10	—	ns	9
50	t _{WH2CL2}	t _{RCS}	Read Command Setup Time	0	—	0	—	0	—	0	—	ns	
51	t _{RL2RL2}	t _{RC}	Random Read or Write Cycle Time	80	—	90	—	110	—	130	—	ns	
52	t _{CL2CL2}	t _{HPC}	Read or Write Cycle Time (EDO (Hyper Page) Mode)	20	—	20	—	25	—	30	—	ns	13,14
53	t _{RL2RL2}	t _{RMW}	Read-Modify-Write Cycle Time	135	—	145	—	165	—	185	—	ns	
54	t _{CL2CL2}	t _{PRMW}	Read-Modify-Write Cycle Time (EDO (Hyper Page) Mode)	80	—	80	—	85	—	95	—	ns	13,14
55	t _{REF}	t _{REF}	Refresh Period	—	8	—	8	—	8	—	8	ms	15
56	t _{RL1AX}	t _{RAH}	Row Address Hold Time	8	—	8	—	8	—	8	—	ns	
57	t _{AVRL2}	t _{ASR}	Row Address Setup Time	0	—	0	—	0	—	0	—	ns	
58	t _T	t _T	Transition Time (Rise and Fall)	2	50	2	50	2	50	2	50	ns	4,5
59	t _{WL1WH1}	t _{WPZ}	WE Pulse Width for Disable When CAS High	5	—	7	—	7	—	7	—	ns	
60	t _{CL1WH1}	t _{WCH}	Write Command Hold Time	10	—	10	—	10	—	15	—	ns	
61	t _{WL1WH1}	t _{WP}	Write Command Pulse Width	10	—	10	—	10	—	15	—	ns	
62	t _{WL1CL2}	t _{WCS}	Write Command Setup Time	0	—	0	—	0	—	0	—	ns	11
63	t _{WL1CH1}	t _{CWL}	Write Command to CAS Lead Time	15	—	15	—	15	—	20	—	ns	
64	t _{WL1RH1}	t _{RWL}	Write Command to RAS Lead Time	15	—	15	—	15	—	20	—	ns	

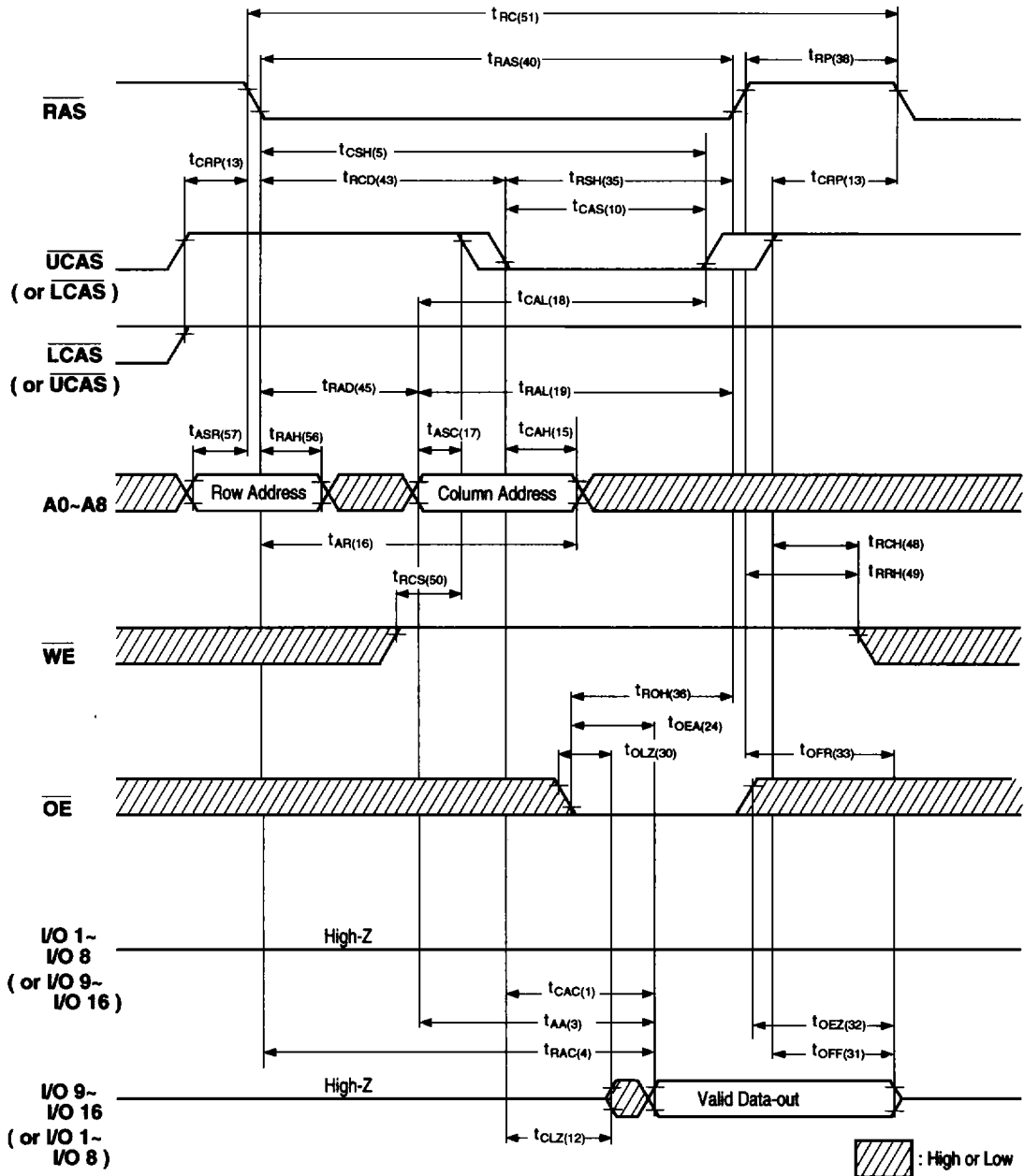
Notes:

3. Eight Initialization Cycles are required following a 200μs pause after Power Up. These Initialization Cycles may consist of any combination of the following : RAS only refresh Cycles, Read Cycles, Write Cycles, CAS before RAS refresh Cycles.
4. AC measurements assume $t_T=3\text{ns}$. All AC parameters are measured with $V_{IL}(\text{min.}) \geq V_{SS}$ and $V_{IH}(\text{max.}) \leq V_{CC}$ and with a load equivalent to two TTL loads and 100pF.
5. $V_{IH}(\text{min.})$ and $V_{IL}(\text{max.})$ are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
6. Operation within the $t_{RCD}(\text{max.})$ limit ensures that $t_{RAC}(\text{max.})$ can be met. $t_{RCD}(\text{max.})$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD}(\text{max.})$ limit, then access time is controlled by t_{CAC} .
7. Operation within the $t_{RAD}(\text{max.})$ limit ensures that $t_{RAC}(\text{max.})$ can be met. $t_{RAD}(\text{max.})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD}(\text{max.})$ limit, then access time is controlled by t_{AA} .
8. Assumes three state test load (5pF and a 220 ohm to 1.3V Thevenin equivalent).
9. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
10. $t_{OFF}(\text{max.})$ defines the time at which the output achieves an open circuit condition and is not referenced to output voltage levels.
11. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{WCS} \geq t_{WCS}(\text{min.})$, the cycle is an early write cycle and data-out pins will remain open circuit (high impedance) throughout the entire cycle. If $t_{RWD} \geq t_{RWD}(\text{min.})$, $t_{CWD} \geq t_{CWD}(\text{min.})$ and $t_{AWD} \geq t_{AWD}(\text{min.})$, the cycle is a read-modify-write cycle and the data-out will contain data read from the selected cell. If neither of the above conditions is satisfied, the condition of the data-out (at access time) is indeterminate.
12. These parameters are referenced to $\overline{\text{CAS}}$ leading edge in early write cycles and to $\overline{\text{WE}}$ leading edge in read-modify-write cycles.
13. Access time is determined by the longer of t_{AA} , t_{CAC} , or t_{CPA} .
14. $t_{ASC} \geq t_{CP}$ to achieve $t_{PC}(\text{min.})$ and $t_{CPA}(\text{max.})$ values.
15. $t_{REF}=128\text{msec}$ for Long Refresh version (L version).
16. t_{OFR} applies only when $\overline{\text{CAS}}$ is high.

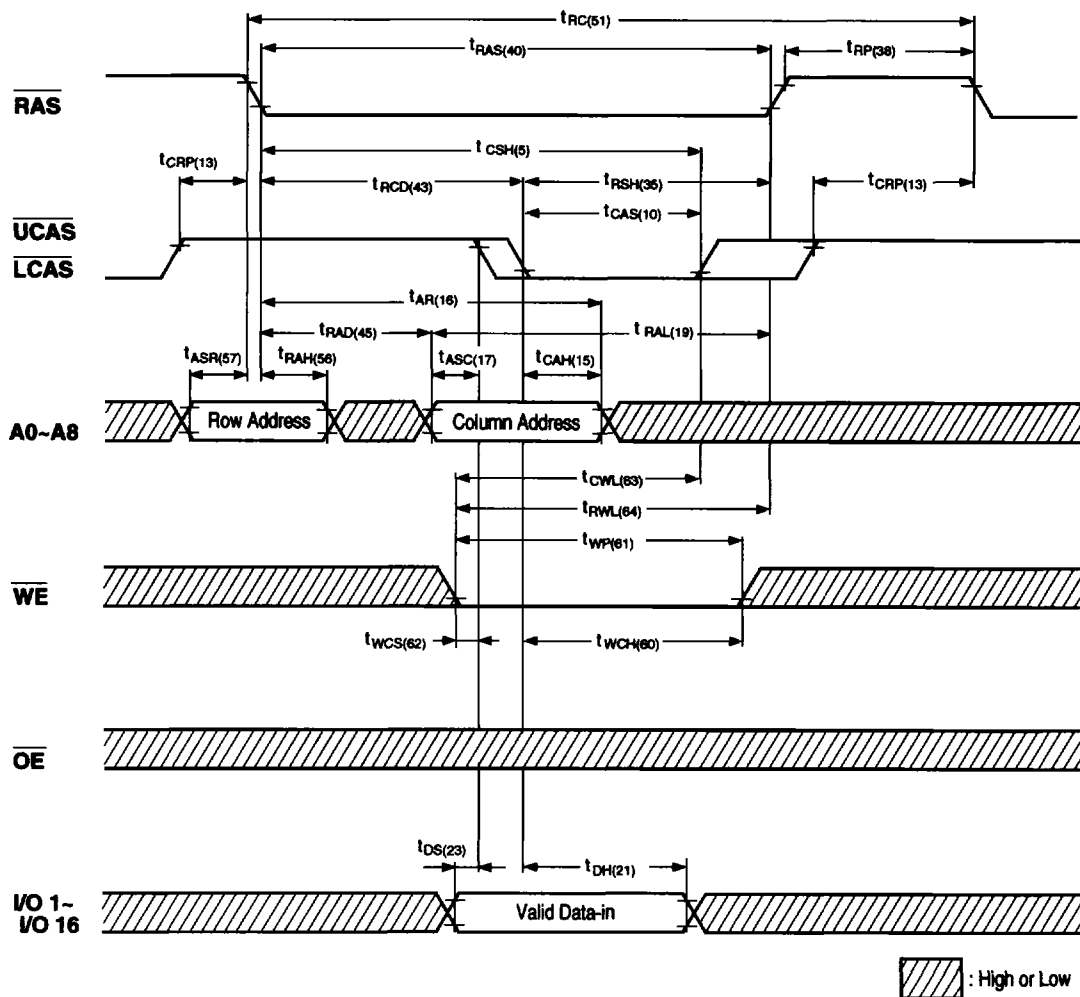
WORD READ CYCLE



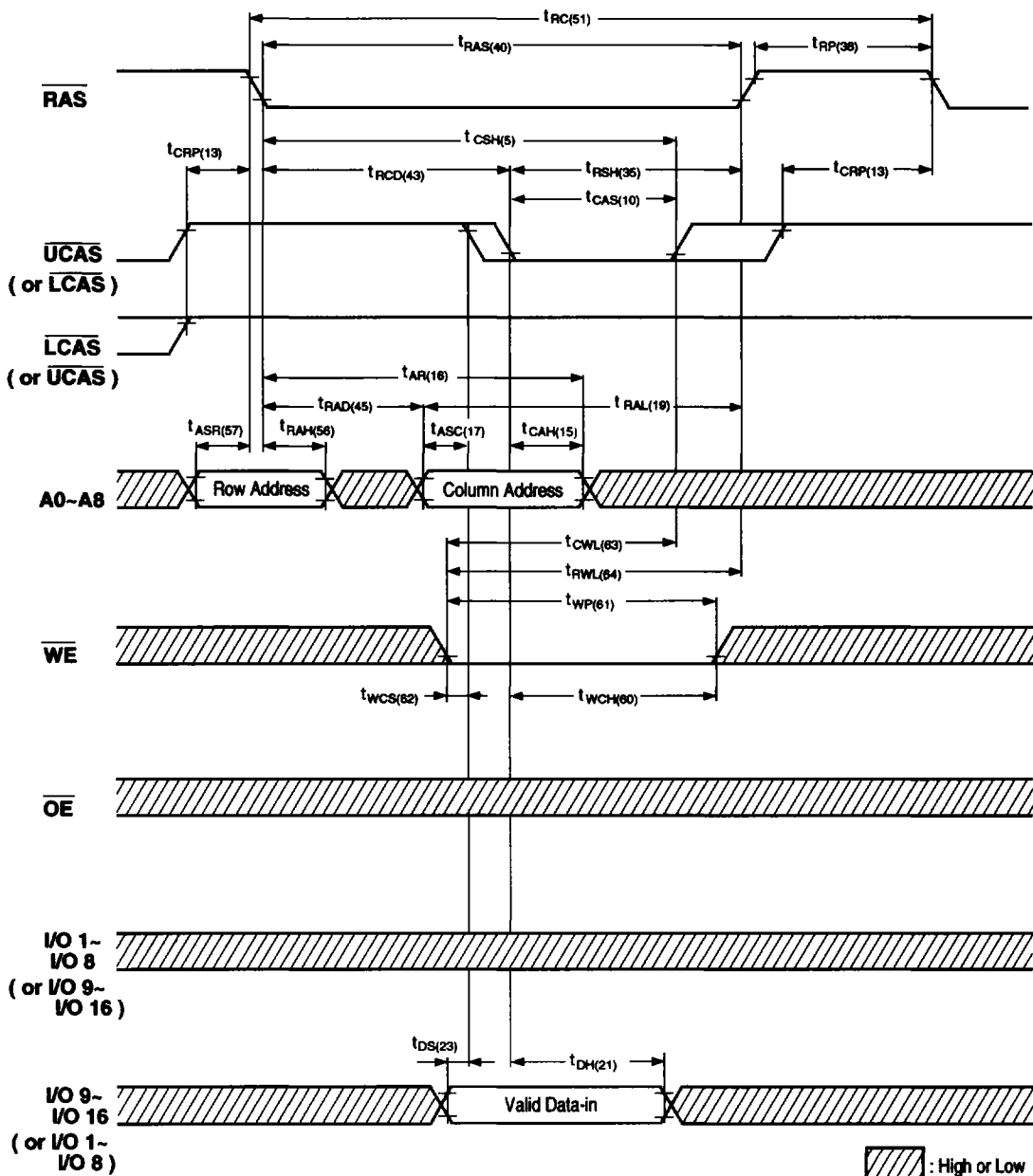
BYTE READ CYCLE



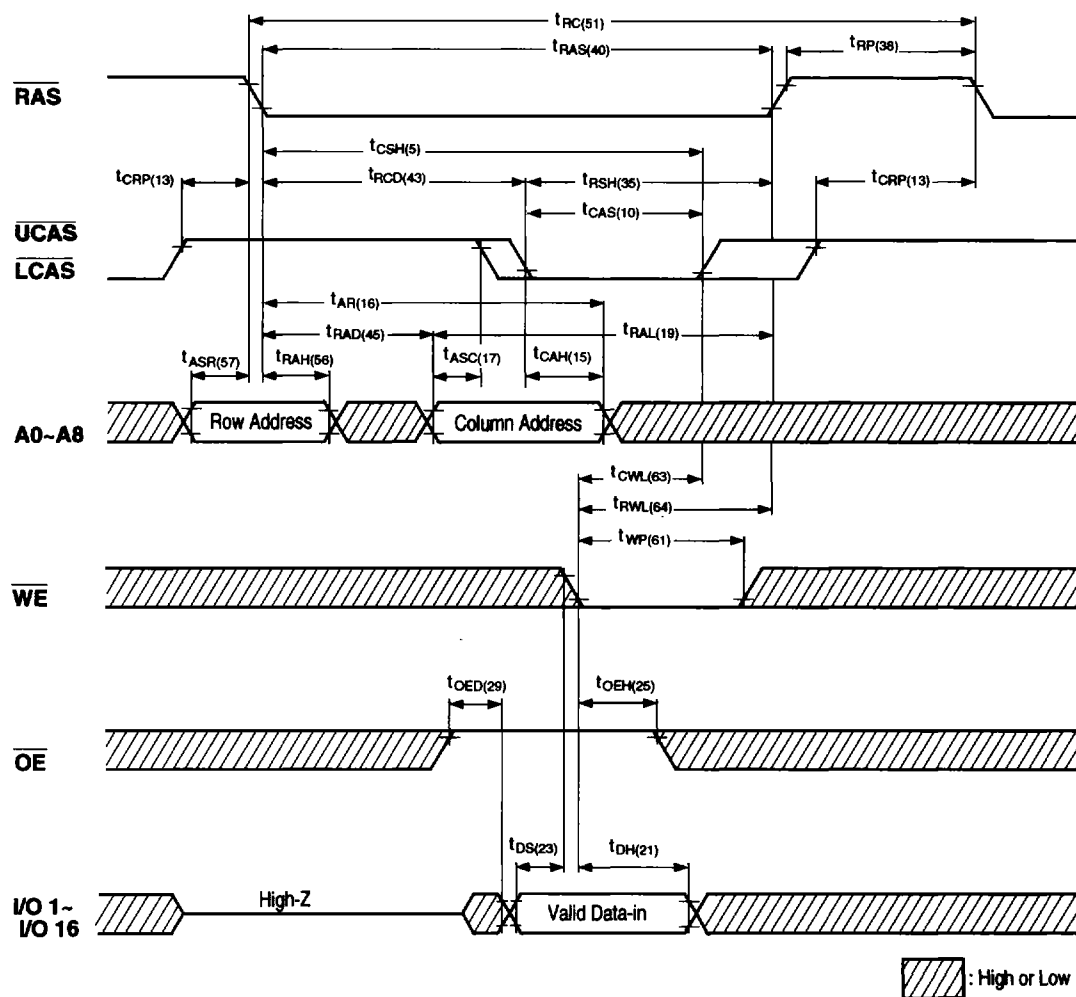
WORD WRITE CYCLE (EARLY WRITE)



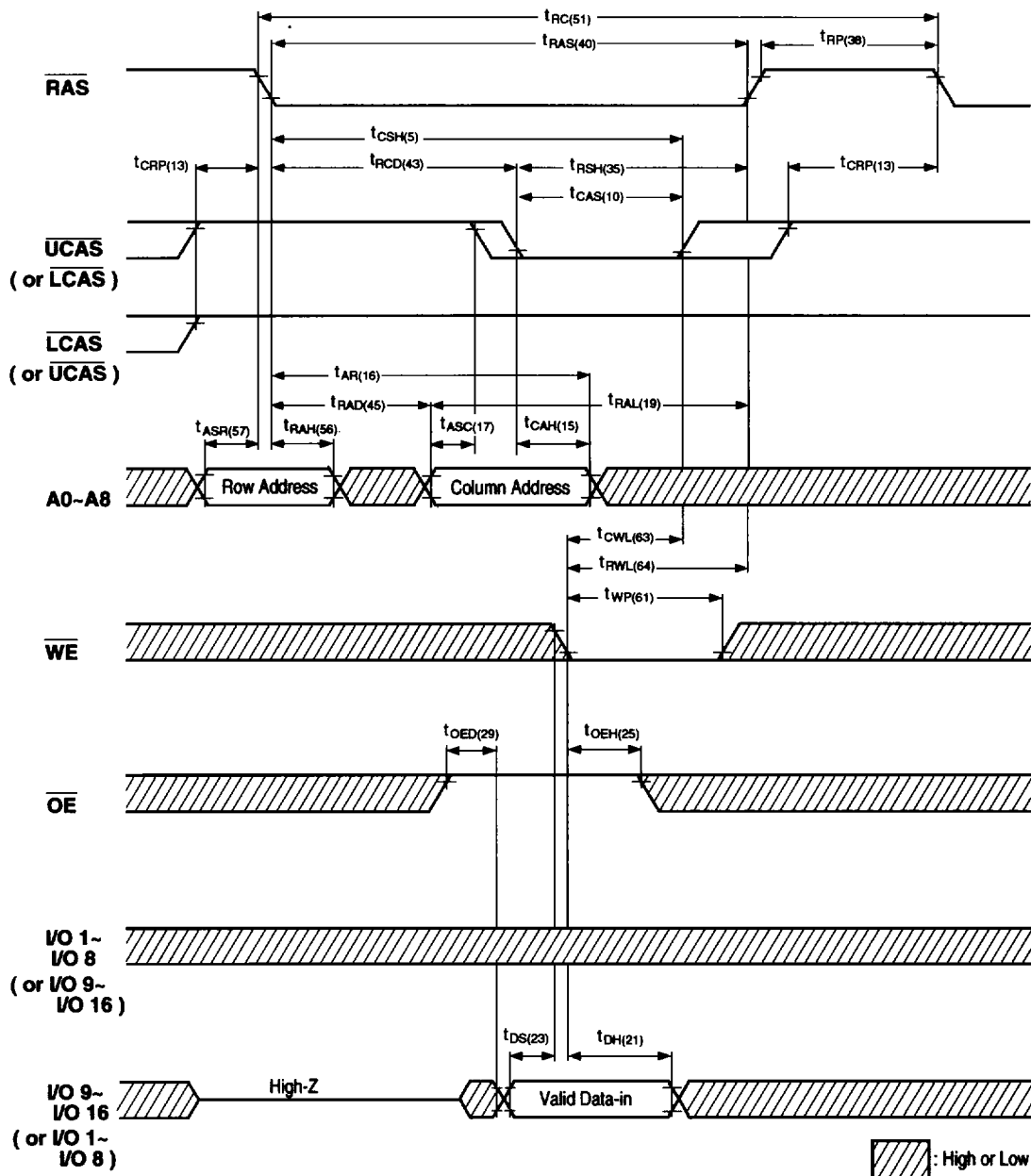
BYTE WRITE CYCLE (EARLY WRITE)



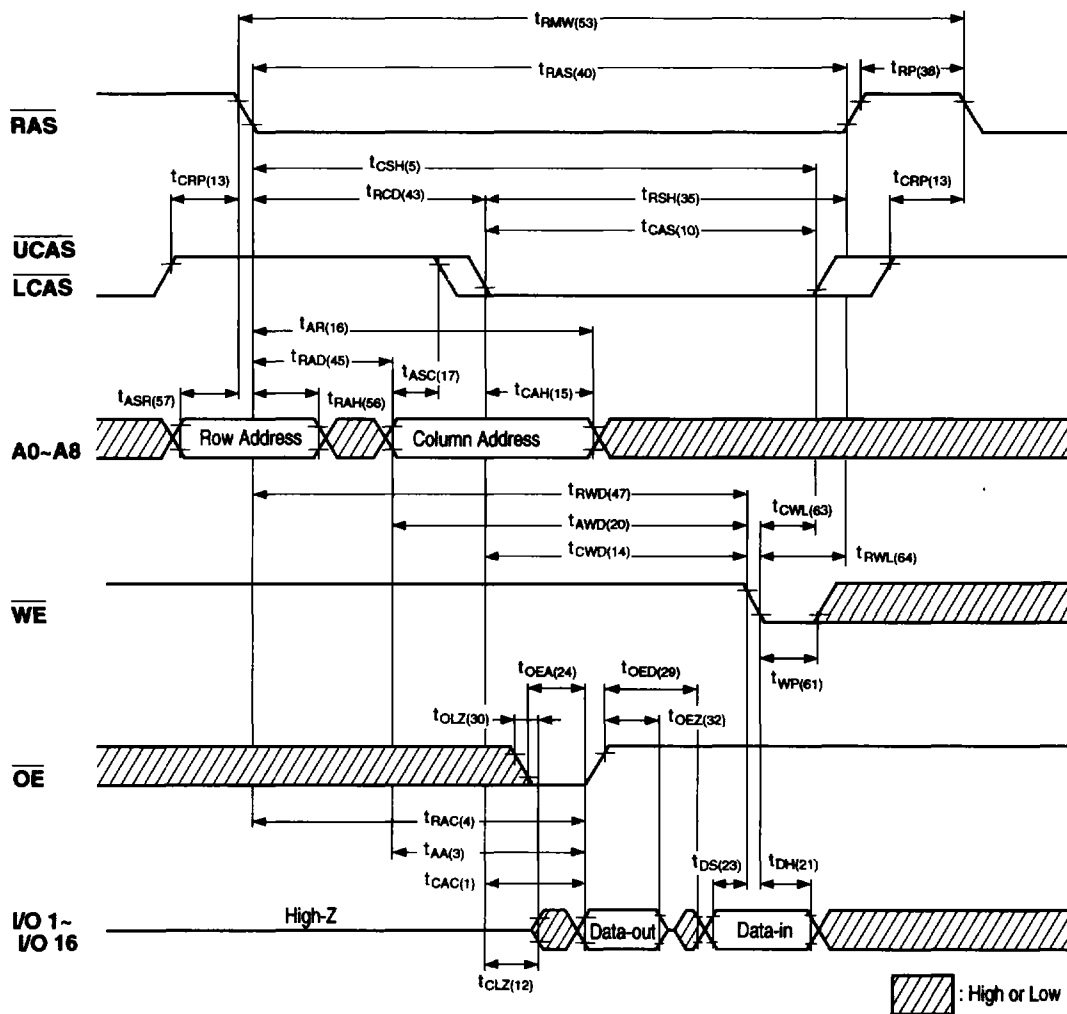
WORD WRITE CYCLE ($\overline{\text{OE}}$ -CONTROLLED WRITE)



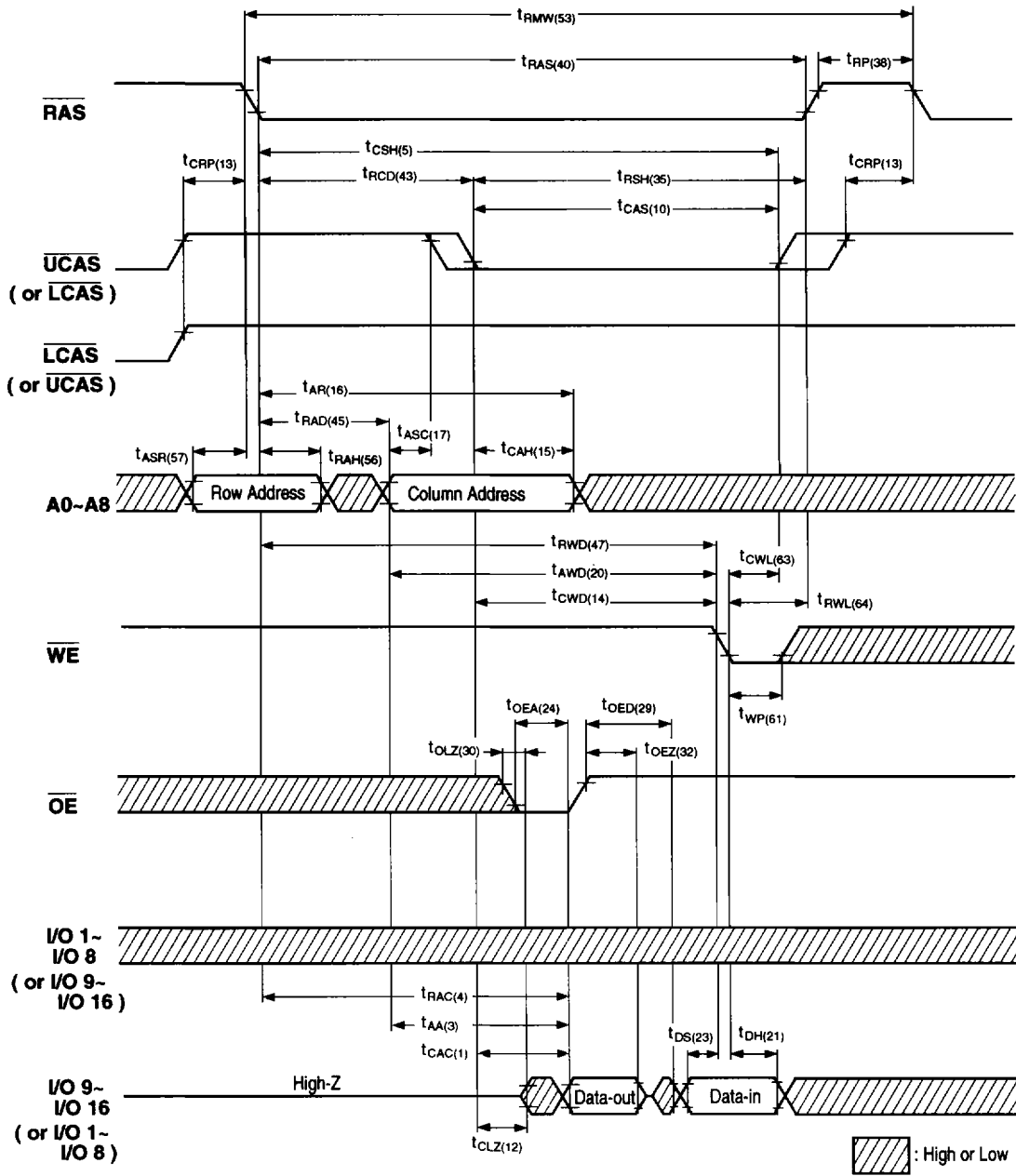
BYTE WRITE CYCLE (OE-CONTROLLED WRITE)



WORD READ-MODIFY-WRITE CYCLE



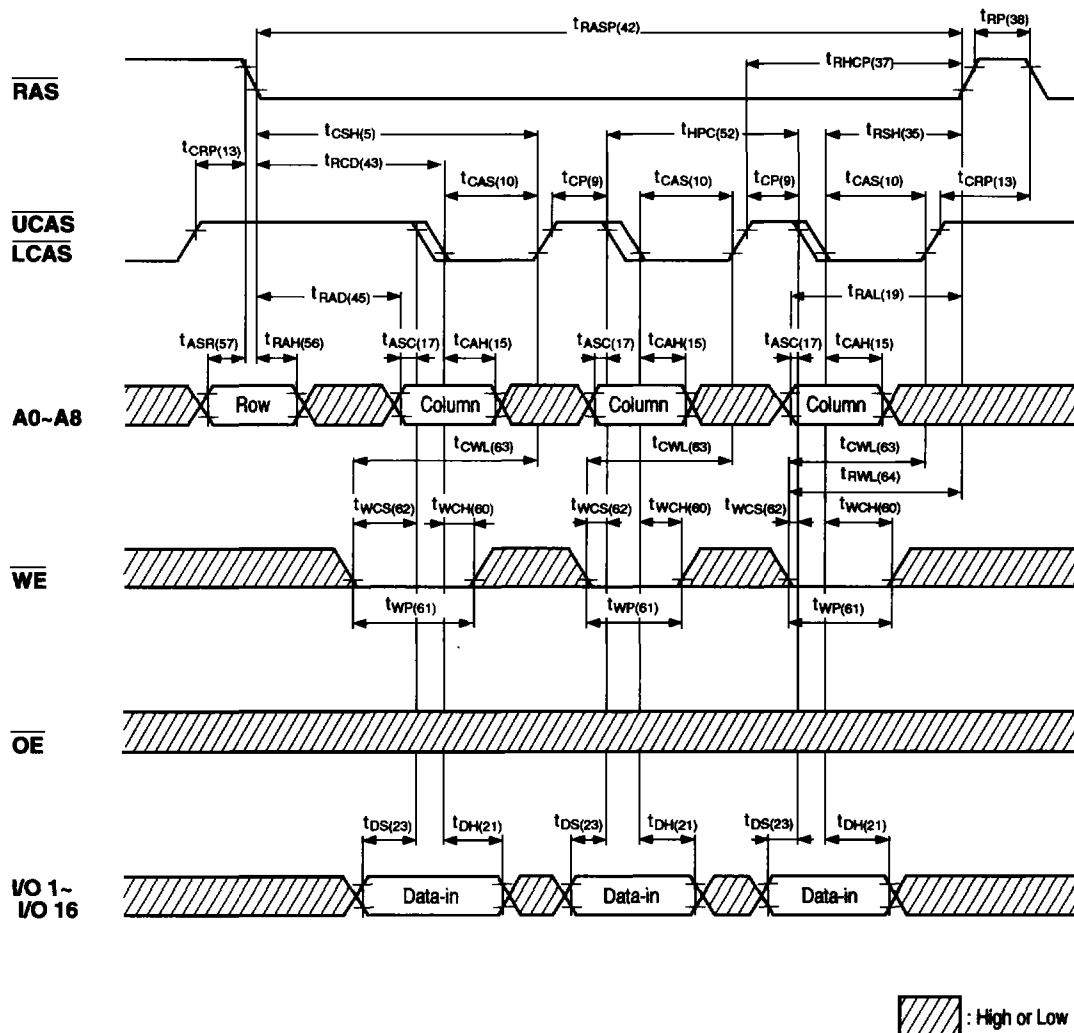
BYTE READ-MODIFY-WRITE CYCLE



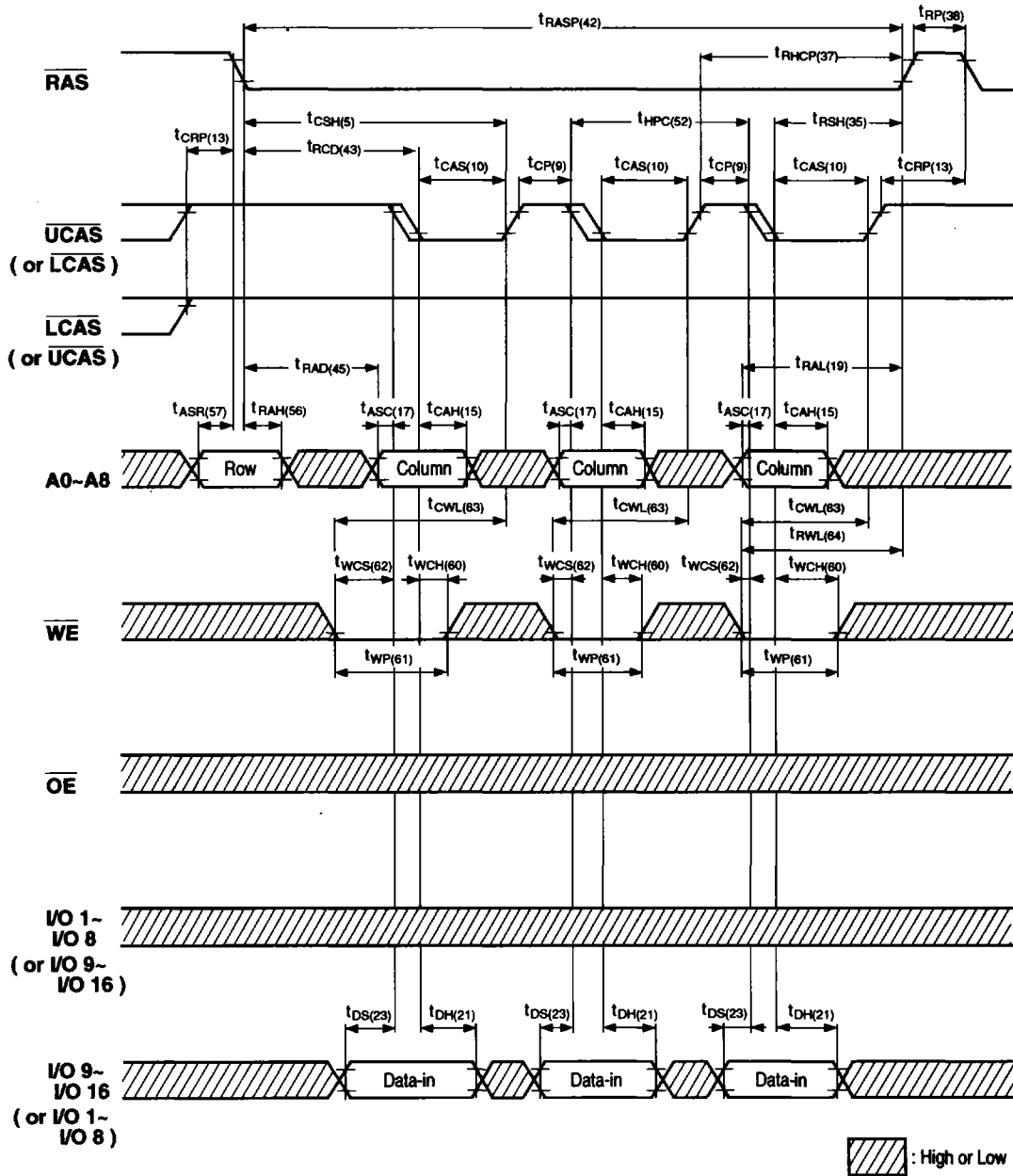
EDO (HYPER PAGE) MODE BYTE READ CYCLE



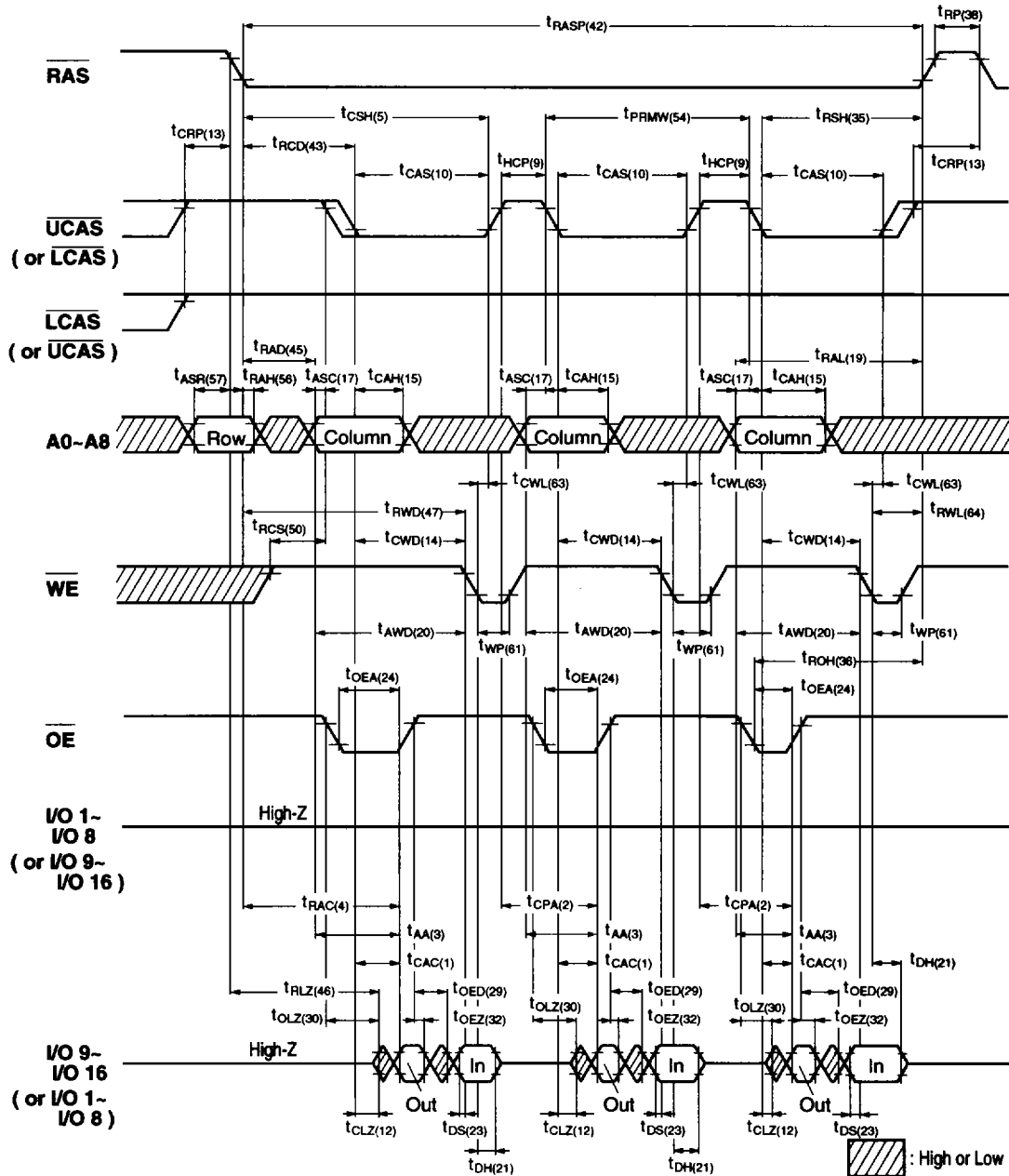
EDO (HYPER PAGE) MODE EARLY WORD WRITE CYCLE



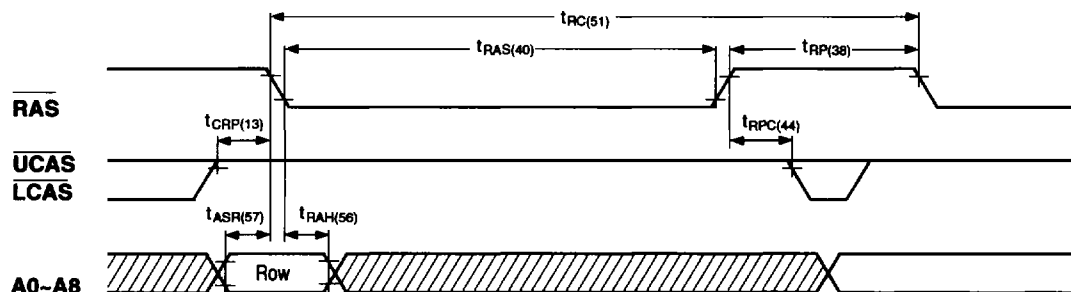
EDO (HYPER PAGE) MODE EARLY BYTE WRITE CYCLE



EDO (HYPER PAGE) MODE BYTE READ-MODIFY-WRITE CYCLE



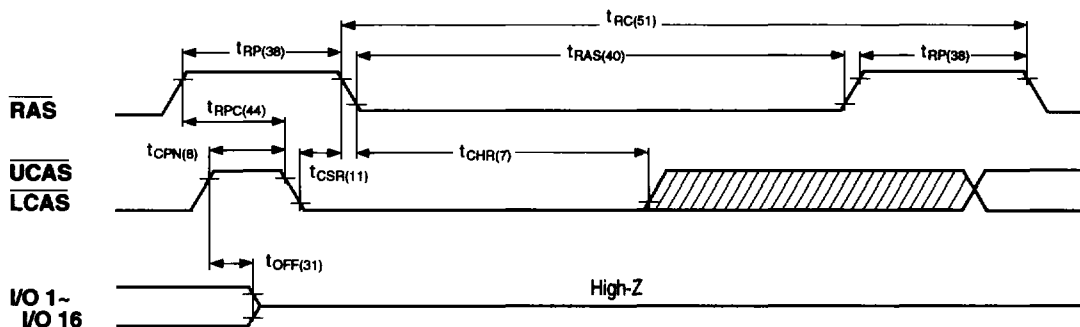
RAS ONLY REFRESH CYCLE



Note: $\overline{WE}$, $\overline{OE}$ = Don't care.

: High or Low

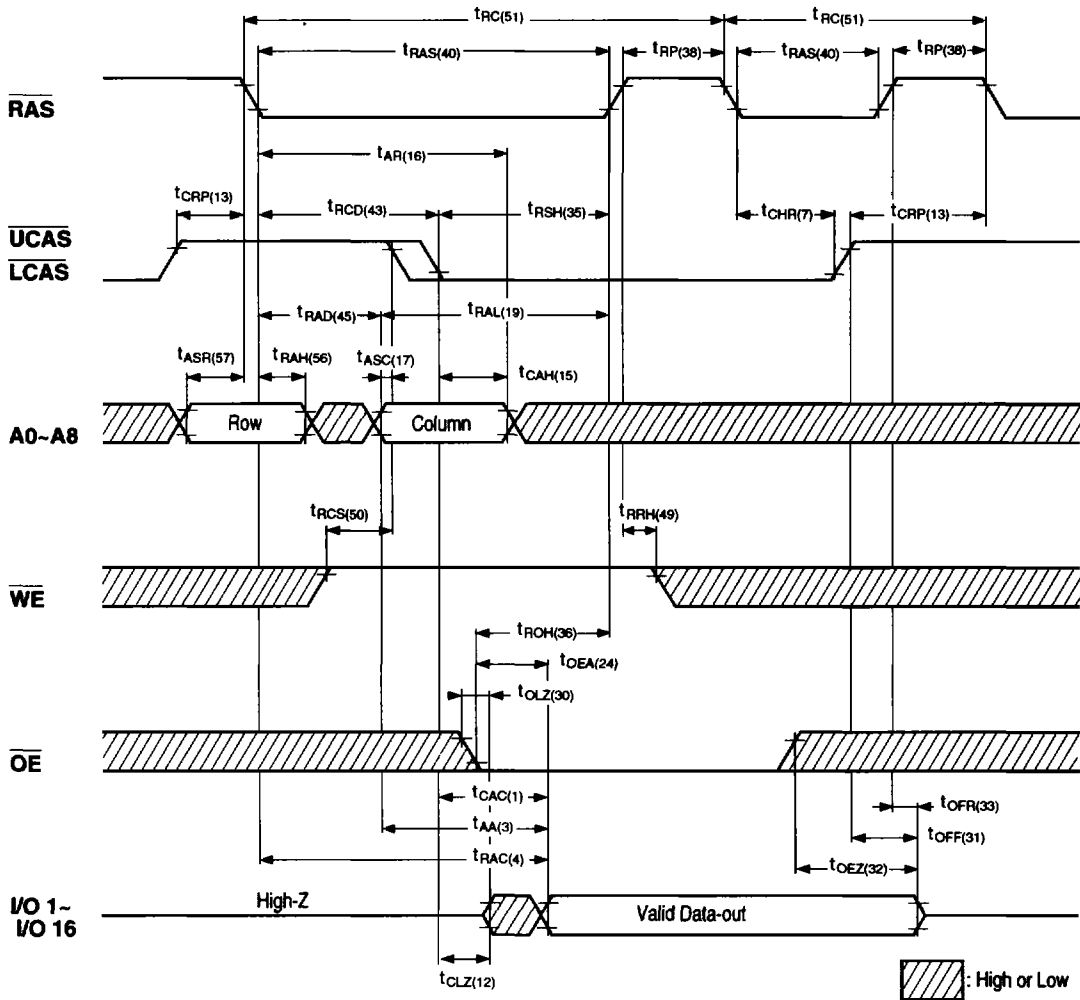
CAS BEFORE RAS REFRESH CYCLE



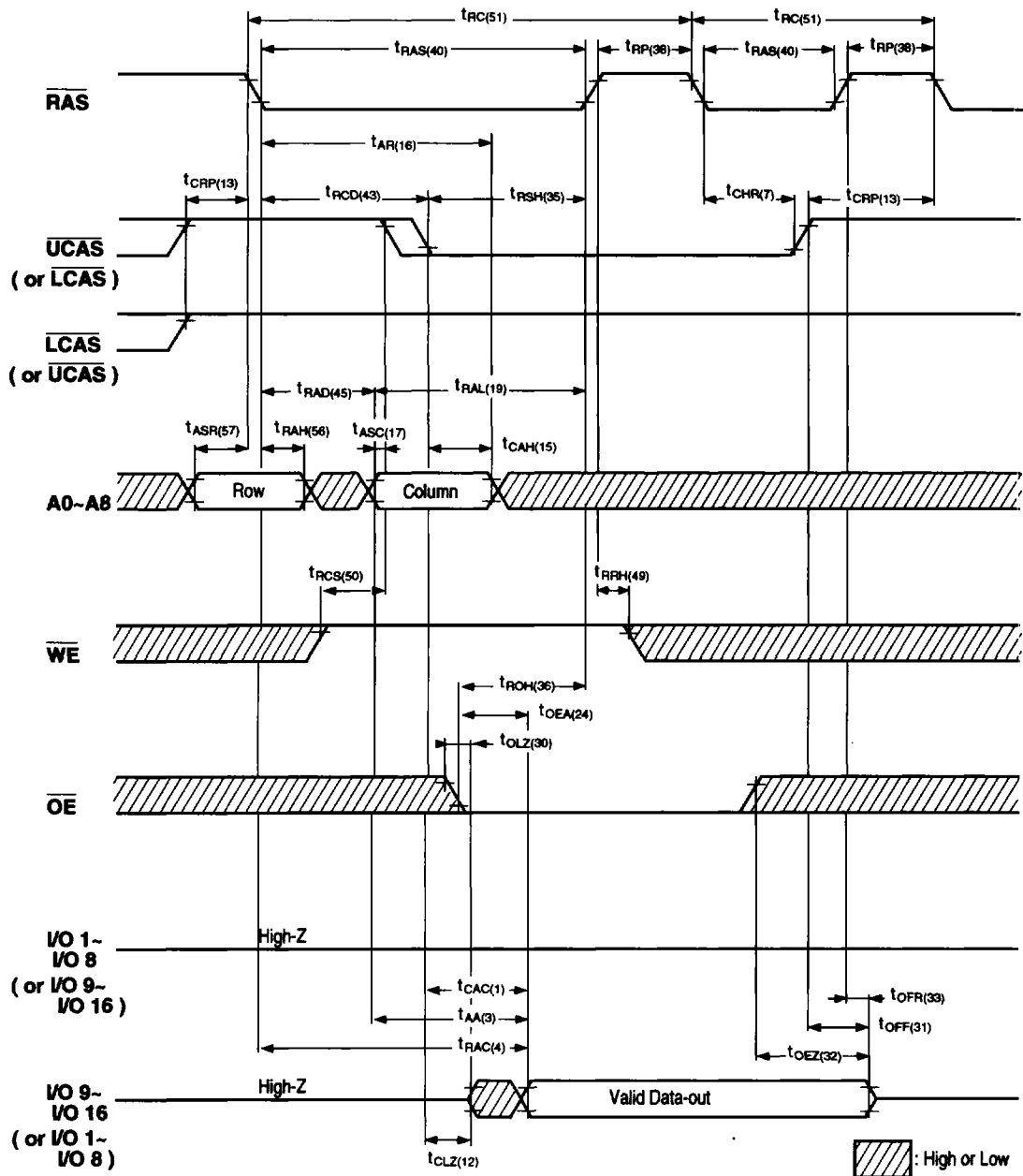
: High or Low

Note: $\overline{OE}$, A0~A8 = Don't care.

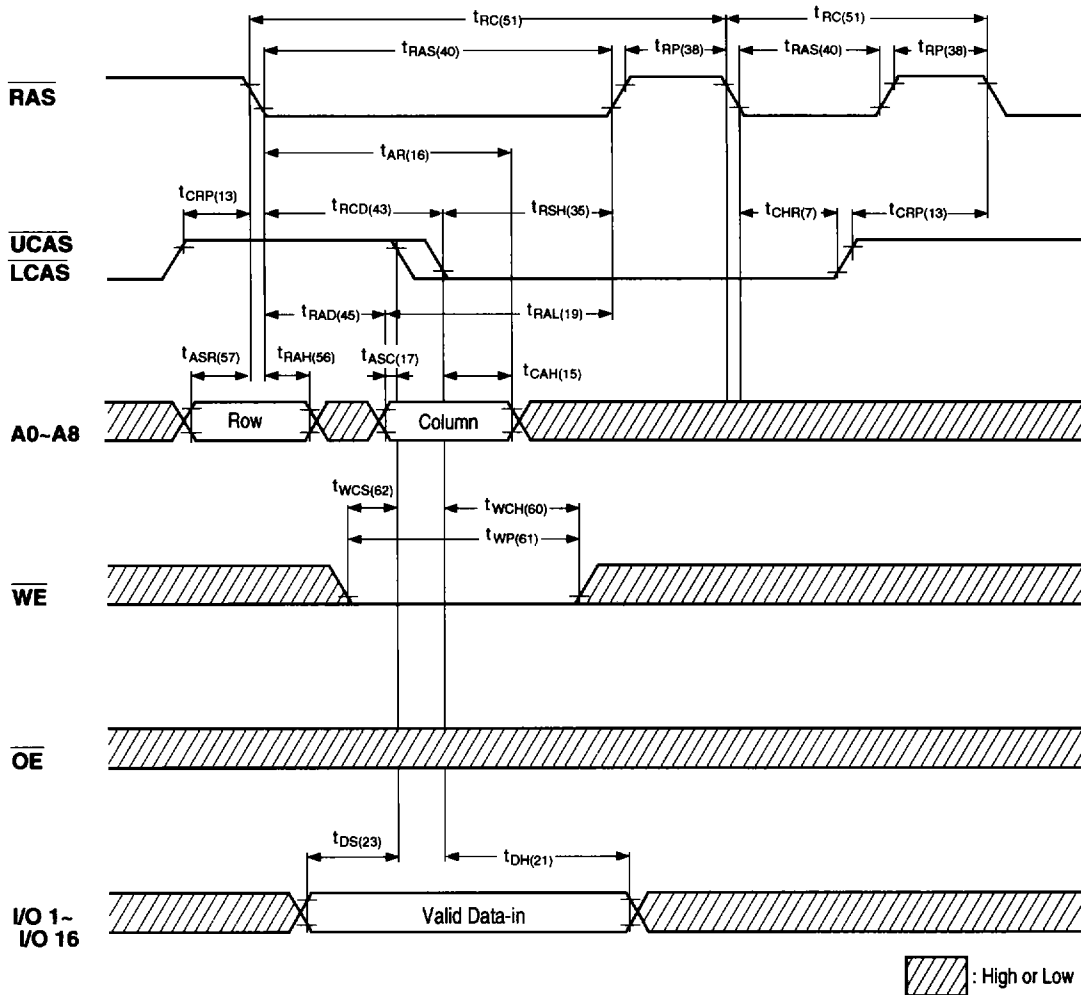
HIDDEN REFRESH CYCLE (WORD READ)



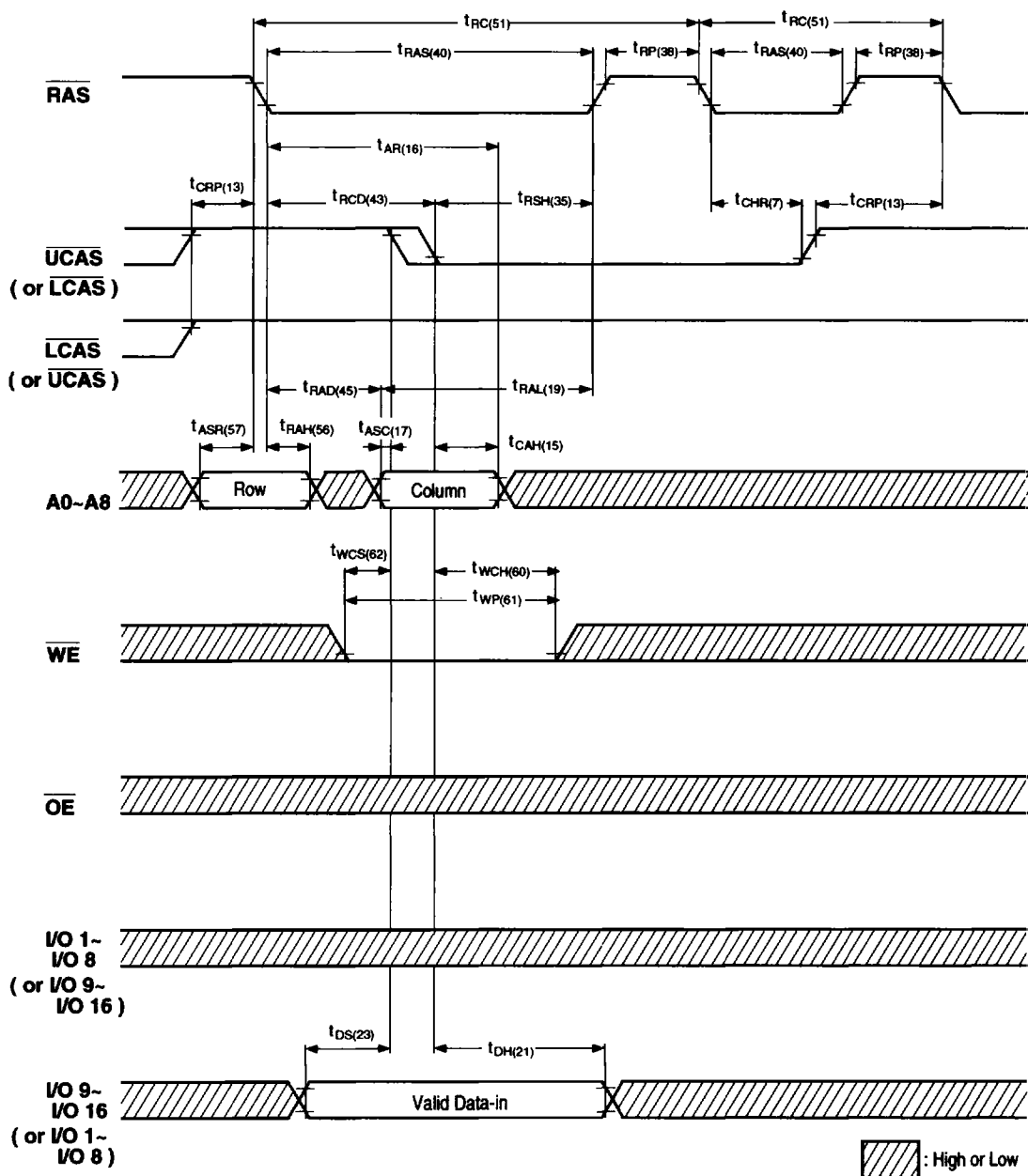
HIDDEN REFRESH CYCLE (BYTE READ)



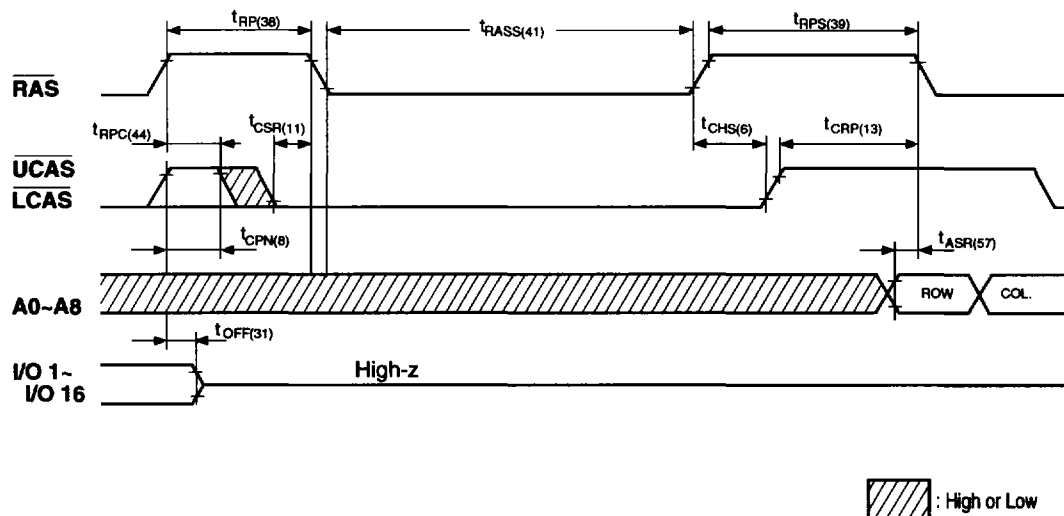
HIDDEN REFRESH CYCLE (EARLY WORD WRITE)



HIDDEN REFRESH CYCLE (EARLY BYTE WRITE)



SELF REFRESH MODE



■ The NN514265L/AL version has a Self Refresh Mode.

a. Entering the Self Refresh Mode:

The NN514265L/AL Self Refresh Mode is entered by using $\overline{CAS}$ before $\overline{RAS}$ cycle and holding $\overline{RAS}$ and $\overline{CAS}$ signal "low" longer than 300 μ s.

b. Continuing the Self Refresh Mode:

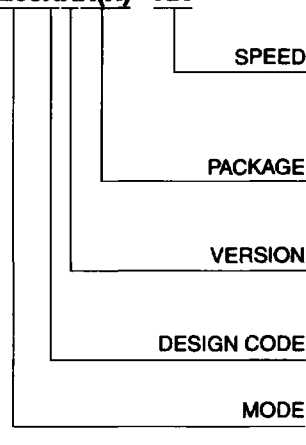
The Self Refresh Mode is continued by holding $\overline{RAS}$ "low" after entering the Self Refresh Mode. It does not depend on $\overline{CAS}$ being "high" or "low" after entering the Self Refresh Mode to continue the Self Refresh Mode.

c. Exiting the Self Refresh Mode:

The NN514265L/AL exits the Self Refresh Mode when the $\overline{RAS}$ signal is brought "high".

ORDERING INFORMATION

NN514265XXX(X) - XX

	SPEED	45 : 45ns 50 : 50ns 60 : 60ns 70 : 70ns
	PACKAGE	J : Plastic SOJ TT : Plastic TSOP TYPEII
	VERSION	BLANK : Standard Version L : Long Refresh Version 128ms Refresh
	DESIGN CODE	BLANK : NN514265 series A : NN514265A series
	MODE	4265 : EDO (Hyper Page) 2CAS ,256K x 16 ,512refresh cycle